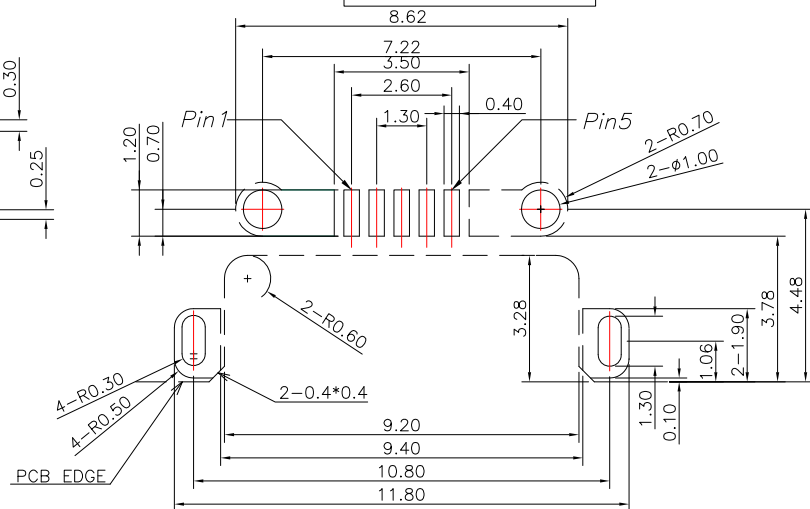
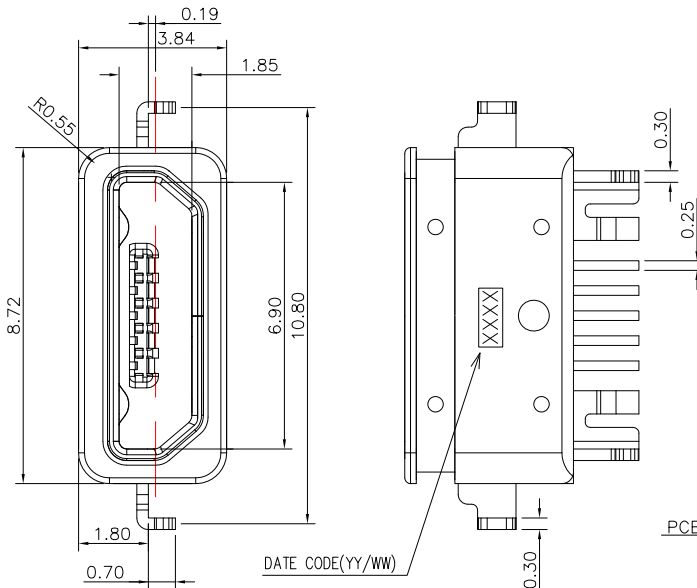
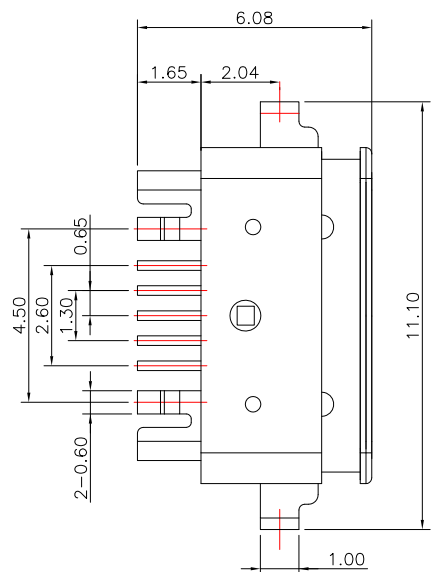
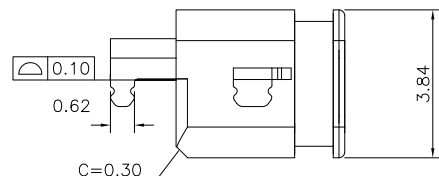


IP67



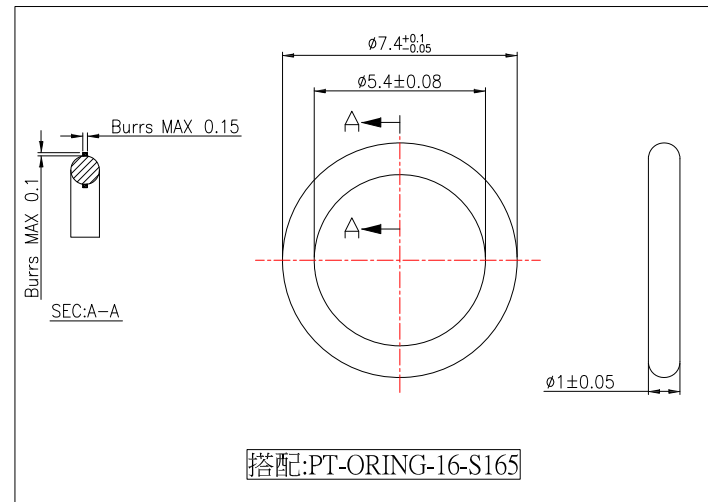
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
- 3.1 RATING: 1.0A
 - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920
5	刪除O-RING圖	Jack	040819
4	更新樣式	Jack	032119
3	新增O-RING圖	Jack	112618
2	新增尺寸	Jack	073118
1	更新為A0版	Jack	071718
ITEM NO.	DESCRIPTION	DRAWN	DATE

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

UNITS: MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	10/29/20		MODLE	MICRO USB 5PF B TYPE 沉板上 H 1.8 IP67
CHECKED BY:	DATE	FINISH	DWG NO.	MRUSB-5B-WP13-x-S165
Jacky Chen	10/29/20	SCALE	1 : 1	SIZE: A4
APPROVED BY:	DATE	SHEET NO.	PART NO.	MRUSB-5B-WP13-x-S165
Tony Kao	10/29/20	1 of 1		VER: R6